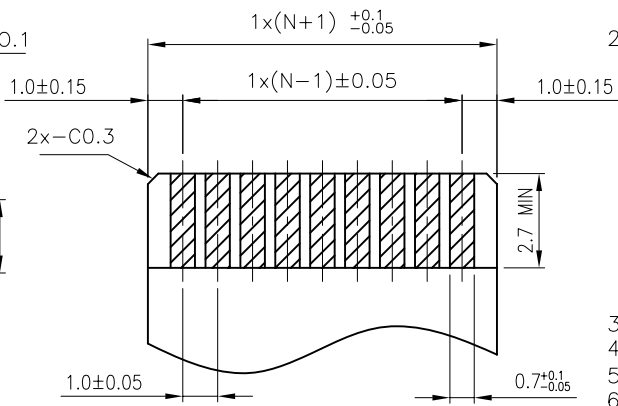


PCB. PATTERN LAYOUT



APPLICABLE RECOMMENDED LAYOUT
(THICKNESS:0.3±0.03)

- NOTES:
- MATERIAL:
 - HOUSING: THERMOPLASTIC, HIGH TEMP.,UL94V-0;
 - CONTACT: COPPER ALLOY
 - FITTING NAIL: COPPER ALLOY
 - FINISH:
 - CONTACT:
 - 50u" MIN. NICKEL UNDERPLATING OVERALL.
 - 1: GOLD FLASH.
 - N: 100u" MIN MATT TIN.
 - L: 100u" MIN PURE TIN.
 - FITTING NAIL:
 - 50u" MIN. NICKEL UNDERPLATING OVERALL.
 - 1: GOLD FLASH.
 - N: 100u" MIN MATT TIN.
 - L: 100u" MIN PURE TIN.
 - REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
 - SPEC. PLS. REFER TO SPEC-50642-XXXX-XXX.
 - PACKAGE PLS. REFER TO 88204-(XX+1)CR.
 - OTHER: SHELL ALIGNMENT LINES,BULGE 0.05mm MAX.
 - PART NUMBER.

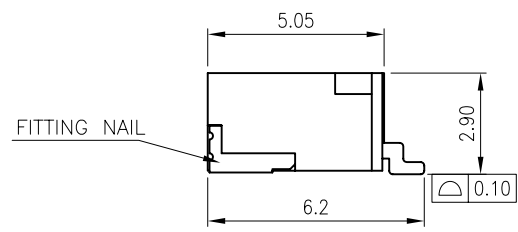
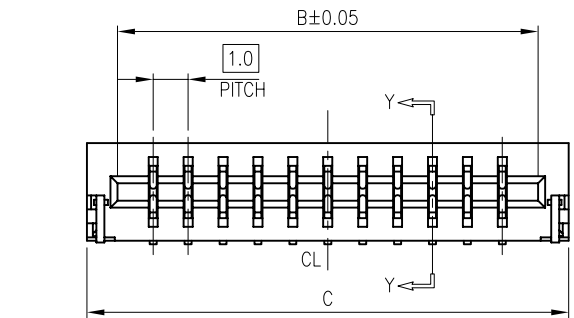
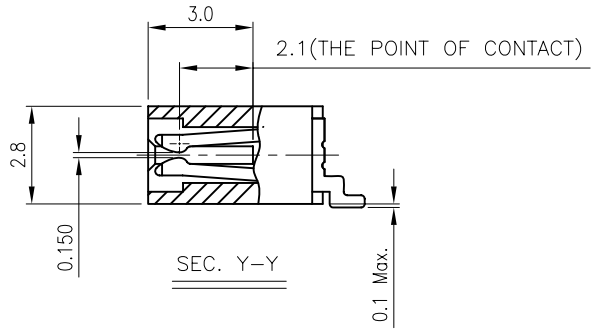
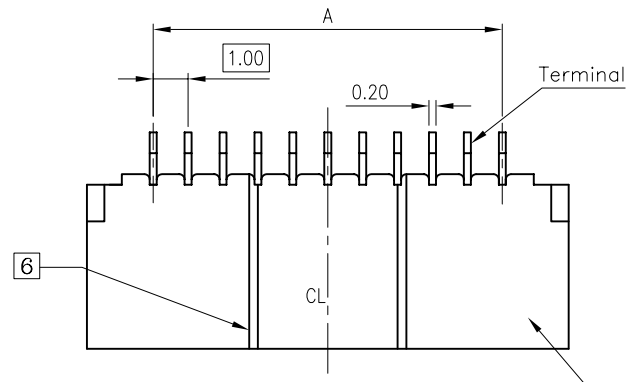
P/N LEGEND

50646-XXX	X	X	-XXX	XXX	Housing MAT.	Housing Color.
				001	HF PLASTIC	BLACK

NO OF CONTACT
PACKING
0:TAPE&REEL
1:TUBE

PLATING
N:MATT TIN(LEAD FREE)
L:PURE TIN(LEAD FREE)
1:GOLD FLASH(LEAD FREE)

CKT	Dim A	Dim B	Dim C	CKT	Dim A	Dim B	Dim C
4	3.0	5.05	6.8	18	17.0	19.05	20.8
5	4.0	6.05	7.8	19	18.0	20.05	21.8
6	5.0	7.05	8.8	20	19.0	21.05	22.8
7	6.0	8.05	9.8	21	20.0	22.05	23.8
8	7.0	9.05	10.8	22	21.0	23.05	24.8
9	8.0	10.05	11.8	23	22.0	24.05	25.8
10	9.0	11.05	12.8	24	23.0	25.05	26.8
11	10.0	12.05	13.8	25	24.0	26.05	27.8
12	11.0	13.05	14.8	26	25.0	27.05	28.8
13	12.0	14.05	15.8	27	26.0	28.05	29.8
14	13.0	15.05	16.8				
15	14.0	16.05	17.8				
16	15.0	17.05	18.8				
17	16.0	18.05	19.8				



QUALITY SYMBOLS MAJOR Ⓢ CRITICAL Ⓢ GENERAL TOLERANCES (UNLESS SPECIFIED) X. ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	DRAWN BY Liang,lin ji CHECKED BY Lu, jing quan APPROVED BY hsieh,fu yu	DATE 18/10/10 DATE 18/10/10 DATE 18/10/10	 1.0mm NON-ZIF FPC CONN. SMT R/A B/C TYPE	UNITS mm SCALE 1:4	 SIZE A4 REV D	RFG NO. PART NO. DWG NO. 50646-XXXX-XXX
	TITLE 1.0mm NON-ZIF FPC CONN. SMT R/A B/C TYPE					